Electrical Datasheet*

GB05SHT12-CAL

Silicon Carbide Power Schottky Diode Chip

Features

- 1200 V Schottky rectifier
- 250 °C maximum operating temperature
- Temperature independent switching behavior
- · Superior surge current capability
- Positive temperature coefficient of V_F
- Extremely fast switching speeds
- Superior figure of merit Q_C/I_F



Maximum Ratings at T_j = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V_{RRM}		1200	V
Continuous forward current	I _F	T _C ≤ 215 °C	5	Α
RMS forward current	I _{F(RMS)}	T _C ≤ 215 °C	8	Α
Operating and storage temperature	T_{j} , T_{stg}		-55 to 250	°C

Electrical Characteristics at T_j = 250 °C, unless otherwise specified

Davamatav	Cumbal	Conditions		Values			I I m ! 4
Parameter	Symbol			min.	typ.	max.	Unit
Diode forward voltage	V _F	I _F = 5 A, T _j = 25 °C I _F = 5 A, T _i = 210 °C		2.1 3.5		V	
Reverse current	I _R	$V_R = 1200 \text{ V}, T_j = 25 \text{ °C}$ $V_R = 1200 \text{ V}, T_j = 250 \text{ °C}$		0.9 20.8	10 150	μΑ	
Total capacitive charge	Q _C		V _R = 400 V V _R = 960 V		17 29		nC
Switching time	t _s	- dI _F /dt = 200 A/μs Τ _j = 210 °C	V _R = 400 V V _R = 960 V		< 25		ns
Total capacitance	С	$V_R = 1 \text{ V, } f = 1 \text{ MHz, } T_j = 25 \text{ °C}$ $V_R = 400 \text{ V, } f = 1 \text{ MHz, } T_j = 25 \text{ °C}$ $V_R = 1000 \text{ V, } f = 1 \text{ MHz, } T_j = 25 \text{ °C}$		237 25 20		pF	

Thermal Characteristics

Thermal resistance, junction - case	R _{thJC}	Assuming TO-276 package	1.38	°C/W

^{*}For chip size and metallization, please refer to the mechanical datasheet (must have a non-disclosure agreement with GeneSiC Semiconductor).

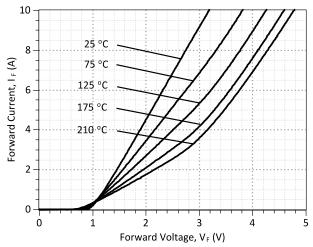


Figure 1: Typical Forward Characteristics

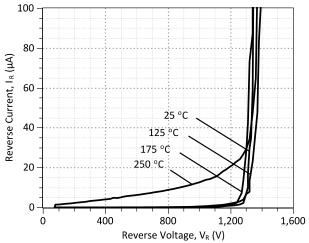


Figure 2: Typical Reverse Characteristics

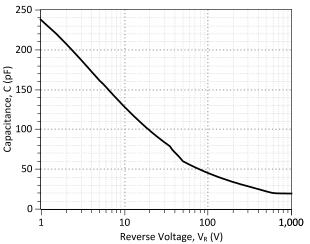


Figure 3: Typical Junction Capacitance vs Reverse Voltage Characteristics

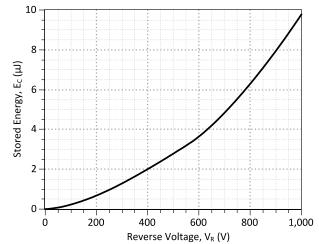


Figure 4: Typical Switching Energy vs Reverse Voltage Characteristics

Revision History					
Date	Revision	Comments	Supersedes		
2012/04/03	0	Initial release			

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SPICE Model Parameters

Copy the following code into a SPICE software program for simulation of the GB05SHT12-CAL device.

```
MODEL OF GeneSiC Semiconductor Inc.
    $Revision: 1.0
                               $
     $Date: 05-SEP-2013
    GeneSiC Semiconductor Inc.
     43670 Trade Center Place Ste. 155
    Dulles, VA 20166
    httphttp://www.genesicsemi.com/index.php/sic-products/schottky
    COPYRIGHT (C) 2013 GeneSiC Semiconductor Inc.
    ALL RIGHTS RESERVED
* These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
* OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
* TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
* PARTICULAR PURPOSE."
* Models accurate up to 2 times rated drain current.
* Start of GB05SHT12-CAL SPICE Model
.SUBCKT GB05SHT12 ANODE KATHODE
R1 ANODE INT R=((TEMP-24)*0.0021); Temperature Dependant Resistor
D1 INT KATHODE GB05SHT12 25C; Call the 25C Diode Model
D2 ANODE KATHODE GB05SHT12 PIN; Call the PiN Diode Model
.MODEL GB05SHT12 25C D
+ IS 4.45E-15
                                    0.206
                         RS
+ N
         1.18144
                         IKF
                                    112.92
+ EG
         1.2
                         XTI
+ CJO
                                    0.419
         3.00E-10
                        VJ
+ M
         1.6
                         FC
                                    0.5
+ TT
        1.00E-10
1.00E-03
                         BV
                                    1500
+ IBV
                                    1200
                         VPK
+ IAVE
                                    SiC Schottky
                          \mathtt{TYPE}
+ MFG GeneSiC Semiconductor
.MODEL GB05SHT12 PIN D
         2.93E-12
                                   0.35326
+ IS
                          RS
+ N
                                   0.0043236
         4.6113
                         IKF
+ EG
         3.23
                         XTI
                                    60
+ FC
         0.5
                         TT
+ BV
         1500
                         IBV
                                    1.00E-03
+ VPK
         1200
                         IAVE
+ TYPE SiC_PiN
.ENDS
* End of GB05SHT12-CAL SPICE Model
```

Sep 2013